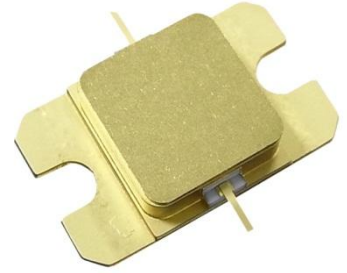


## ■ Features

- High Output Power: Pout=48.0dBm (Typ.)
- High Gain: GL=8.5dB (Typ.)
- High Power Added Efficiency: PAE=32% (Typ.)
- Broad Band: 13.75 to 14.5GHz
- Hermetically Sealed Package



## ■ Description

The SGK1314-60A is a high power GaN-HEMT that is internally matched for standard communication bands to provide optimum power and gain in a 50ohm system.

### ABSOLUTE MAXIMUM RATING (Case Temperature T<sub>c</sub>=25 deg.C)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	26	V
Gate-Source Voltage	V <sub>GS</sub>	-10	V
Total Power Dissipation	P <sub>T</sub>	225	W
Storage Temperature	T <sub>stg</sub>	-55 to +125	deg.C
Channel Temperature	T <sub>ch</sub>	+250	deg.C
Case Temperature	T <sub>case</sub>	-40 to +125	deg.C
Input Power	Pin	<=46	dBm

### RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>		<=24	V
Forward Gate Current	I <sub>GF</sub>	Rg=51ohm	<=20.2	mA
Reverse Gate Current	I <sub>GR</sub>	Rg=51ohm	>=-6.4	mA
Channel Temperature	T <sub>ch</sub>		<+193	deg.C

Note:Electrical specifications are measured under specified test conditions. Not all recommended operating conditions can be guaranteed to meet specifications.

### ELECTRICAL CHARACTERISTICS (Case Temperature T<sub>c</sub>=25 deg.C)

Item	Symbol	Condition	Limit			Unit
			Min.	Typ.	Max.	
Saturated Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V	-	21.0	-	A
Trans Conductance	G <sub>m</sub>	V <sub>DS</sub> =24V, I <sub>DS</sub> =1.8A	-	6.2	-	S
Pinch-off Voltage	V <sub>P</sub>	V <sub>DS</sub> =10V, I <sub>DS</sub> =1.8mA	-	-3.6	-	V
Frequency Range	f		13.75	-	14.5	GHz
Output Power at Pin=43dBm	Pout		47.0	48.0	-	dBm
Linear Gain at Pin=27dBm	GL	V <sub>DS</sub> =24V(typ.)	7.5	8.5	-	dB
Power Gain at Pout=44.5dBm	GP	I <sub>DS(DC)</sub> =1.8A(typ.)	6.0	7.0	-	dB
Drain Current at Pin=43dBm	I <sub>DSR</sub>	Vgs-constant	-	6.6	9.1	A
Power Added Efficiency at Pin=43dBm	PAE		-	32	-	%
Gain Flatness at Pin=27dBm	ΔG		-	-	1.6	dB
3rd Order Intermodulation Distortion	IM <sub>3</sub>	f=13.75GHz, 14.5GHz Δf=10MHz, 2-tone Test Pout=41.5dBm (S.C.L.)	-25.0	-30.0	-	dBc
Thermal Resistance	R <sub>th</sub>	Channel to Case (Tc=25deg.C, P <sub>diss</sub> =43.2W)	-	0.8	1.0	deg.C/W

S.C.L. : Single Carrier Level

CASE STYLE	IBK	
RoHS Compliance	YES	
ESD <sup>*1</sup>	Class 2	2000V to < 4000V

Note : <sup>\*1</sup> Based on ANSI/ESDA/JEDEC JS-001(C=100pF, R=1.5kohm)



## ● Mounting Instructions for Packaged FETs

### 1. Screw Mounting

- (1) The flange of package may be attached using screws. Torque conditions are shown in table 1.

Table1. Recommended and Maximum Torque for Screw Mounting

Package	Recommended Screws	Recommended Torque	Maximum Torque
IB, IBK, IZZ	M3.0	45 N-cm (4.0 in lbf)	50 N-cm (4.4 in lbf)

- (2) The surface finish of the heat sink should be better than 0.8  $\mu\text{m}$ , and the surface flatness must be better than 20  $\mu\text{m}$ .
- (3) Silicon based heat sink compounds should not be used for the thermal conductive grease. They cause poor grounding of the source flange, contamination and long term degradation of thermal resistance between the FET package and heat sink.
- (4) If customers have use of thermal compounds and limited interface materials placed between the package flange and the heatsink to provide thermal transfer, any use of such materials is done at the customer's own risk and must be properly evaluated. Sumitomo Electric uses Panasonic carbon graphite sheet for mounting our devices. Our recommended sheet is EYGS182310. Recommended thickness is 0.1mm. Thermal conductivity is about 700 W/mK in the x-y direction. In the Z direction is about 15 W/mK.

### 2. Soldering for Gate and Drain Terminals

- (1) Recommended solder are Tin-Lead solder (63Sn/37Pb), Lead-Free solder (Sn-3.0Ag-0.5Cu)\*<sup>1</sup> or equivalent.
- (2) For soldering, Tin-Lead solder (63Sn/37Pb) or Lead-Free solder (Sn-3.0Ag-0.5Cu)\*<sup>1</sup> shall be used. (\*1: The figure displays with weight %. A predominantly tin-rich alloy with 3.0% silver and 0.5% copper.)
- (3) Recommended Flux is Rosin type with chlorine content: 0.2% or less and a low halogen content. After soldering, the flux residue should be removed by appropriate cleaning methods.
- (4) The following is shown the recommended soldering conditions.

\* Partial heating method (soldering iron, spot laser/air)

Product terminal temperature: 260 deg.C, max 10 s / terminal or 400 deg.C, max 3 s / terminal

Caution1: Soldering iron must be connected to the ground.

Caution2: Do not rapid cooling the devices.

## Notes & Disclaimer

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.  
This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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